



### AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A substrate processing method comprising:  
preparing a dry substrate having both a metal region and an insulating film on a surface thereof;  
performing during a pre-plating treatment, by bringing a pretreatment liquid into contact with the surface of the substrate to modify the entire surface thereof in such a manner as to:  
remove a metal oxide film from a surface of the metal region and remove residue from a surface of the insulating film; and  
impart a catalyst to the metal region so as to activate the surface of the metal region;  
removing the pretreatment liquid remaining on the surface of the substrate in a rinsing treatment;  
performing an electroless plating process on the surface of the substrate to selectively form an alloy film on the surface of said metal region; and  
post-cleaning and drying the substrate after the electroless plating process ~~and drying the substrate.~~

Claims 2-5 (Cancelled).

6. (Currently Amended) A substrate processing method according to claim 1, wherein said pre-plating treatment and said rinsing treatment ~~are performed by~~ include ejecting a chemical solution or pure water from a nozzle toward the surface of the substrate which faces downwardly.

7. (Currently Amended) A substrate processing method according to claim 6, ~~wherein~~ further comprising rotating the substrate during said pre-plating treatment and said rinsing treatment ~~are performed while the substrate is being rotated.~~

8. (Previously Presented) A substrate processing method according to claim 6, wherein a nozzle used in said pre-plating treatment and a nozzle or nozzles used in said rinsing treatment are connected to respective different flow path systems.

9. (Currently Amended) A substrate processing method according to claim 1, wherein said pre-plating treatment ~~is performed by~~ includes immersing the substrate in the pretreatment liquid.

10. (Currently Amended) A substrate processing method according to claim 1, wherein said rotating comprises rotating the substrate ~~is rotated~~ at a higher speed after said pre-plating treatment is completed.

11. (Currently Amended) A substrate processing method according to claim 5 1, ~~wherein~~ ~~said pre-plating treatment is performed using~~ further comprising preparing the pretreatment liquid ~~which is prepared~~ by mixing together at least ~~together~~ catalytic metal ions and an acid ~~having a function to purify~~ for purifying the surface of the substrate.

12. (Currently Amended) A substrate processing method according to claim 1, wherein said rinsing treatment ~~is performed by~~ includes cleaning the surface of the substrate with pure water or pure water having a reducing capability increased by electrolysis or by dissolving a hydrogen gas.

13. (Currently Amended) A substrate processing method according to claim 1, wherein said rinsing treatment ~~is performed by~~ includes cleaning the surface of the substrate with an aqueous liquid prepared by mixing one component or some components of an electroless plating solution.

14. (Previously Presented) A substrate processing method according to claim 1, wherein said pre-plating treatment and said rinsing treatment are performed in an atmosphere having less oxygen than the atmosphere.

15. (Previously Presented) A substrate processing method according to claim 1, wherein said electroless plating process is performed in an atmosphere having less oxygen than the atmosphere.

16. (Currently Amended) A substrate processing method according to claim 1, ~~wherein~~ further comprising measuring at least one of a film thickness and a film property of said alloy film ~~is measured after said post-cleaning and drying of the substrate is post-cleaned and dried.~~

17. (Currently Amended) A substrate processing method according to claim 1, ~~wherein~~ the further comprising maintaining respective compositions and component concentrations of ~~said the~~ pretreatment liquid and a rinsing liquid therefore, and ~~the~~ a temperature of ~~said the~~ pretreatment liquid ~~are kept~~ in predetermined ranges.

18. (Currently Amended) A substrate processing method according to claim 1, ~~wherein~~ the further comprising measuring a concentration of an impurity mixed in ~~said the~~ pretreatment liquid in said pre-plating treatment ~~is measured~~, and removing the impurity ~~is removed~~ when the impurity reaches a predetermined concentration.

19. (Currently Amended) A substrate processing method according to claim 1, wherein said electroless plating process ~~is performed by~~ includes keeping the temperature, composition, and component concentrations of a plating solution in predetermined ranges, and controlling a plating process time with respect to a predetermined film thickness.

Claims 20-30 (Cancelled).

31. (New) A substrate processing method according to claim 1, wherein the pretreatment liquid comprises an aqueous liquid formed of a mixture of at least one of palladium hydrochloric acid, palladium sulfuric acid, palladium acetic acid, and at least one of a group consisting of hydrochloric acid, sulfuric acid, fluoric acid, acetic acid, oxalic acid, formic acid, citric acid, and tartaric acid.

32. (New) A substrate processing method according to claim 1, wherein the pretreatment liquid comprises an aqueous liquid formed of a mixture of palladium sulfuric acid and sulfuric acid.

33. (New) A substrate processing method according to claim 1, wherein said pre-plating treatment includes bringing the pretreatment liquid into contact with the surface of the substrate in such a manner as to simultaneously remove the metal oxide film, remove the residue, and impart the catalyst.

34. (New) A substrate processing method according to claim 1, wherein said electroless plating process is performed after said removing of the pretreatment liquid remaining on the surface of the substrate.